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Understanding Embedded - PLDs (Programmable Logic Devices)

Embedded - PLDs, or Programmable Logic Devices, are a type of digital electronic component used to build reconfigurable digital circuits. Unlike fixed-function logic devices, PLDs can be programmed to perform specific functions by the user. This flexibility allows designers to customize the logic to meet the exact needs of their applications, making PLDs a crucial component in modern embedded systems.

Applications of Embedded - PLDs (Programmable Logic Devices)

The versatility of PLDs makes them suitable for a wide range of applications. In consumer electronics, PLDs are used to enhance the functionality and performance of

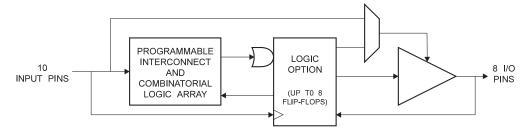
Details	
Product Status	Obsolete
Programmable Type	EE PLD
Number of Macrocells	8
Voltage - Input	5V
Speed	12 ns
Mounting Type	Through Hole
Package / Case	20-DIP (0.300", 7.62mm)
Supplier Device Package	20-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atf16v8cz-12pc

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Figure 1-1. Block Diagram



2. Pin Configuration and Pinouts

Table 2-1. Pinouts - All Pinouts Top View

Pin Name	Function
CLK	Clock
1	Logic Inputs
I/O	Bi-directional Buffers
ŌĒ	Output Enable
VCC	+5V Supply

Figure 2-1. TSSOP

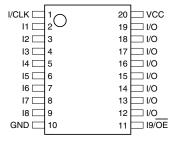


Figure 2-2. DIP/SOIC

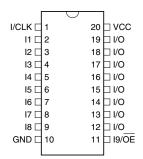
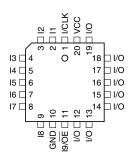


Figure 2-3. PLCC



3. Absolute Maximum Ratings*

Temperature Under Bias40°C to +85°C
Storage Temperature65°C to +150°C
Voltage on Any Pin with Respect to Ground2.0V to +7.0V ⁽¹⁾
Voltage on Input Pins with Respect to Ground During Programming2.0V to +14.0V ⁽¹⁾
Programming Voltage with Respect to Ground2.0V to +14.0V ⁽¹⁾

*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note:

Minimum voltage is -0.6V DC, which may undershoot to -2.0V for pulses of less than 20 ns.
 Maximum output pin voltage is V_{CC} + 0.75V DC, which may overshoot to 7.0V for pulses of less than 20 ns.

4. DC and AC Operating Conditions

	Commercial	Industrial
Operating Temperature (Ambient)	0°C - 70°C	-40°C - 85°C
V _{CC} Power Supply	5V ±5%	5V ±10%

4.1 DC Characteristics

Symbol	Parameter	Condition		Min	Тур	Max	Units
I _{IL}	Input or I/O Low Leakage Current	$0 \le V_{IN} \le V_{IL}(Max)$				-10	μΑ
I _{IH}	Input or I/O High Leakage Current	$3.5 \le V_{IN} \le V_{CC}$				10	μΑ
	Power Supply Current	15 MHz, V _{CC} = Max,	Com			95	mA
I _{CC1}	Power Supply Current	$V_{IN} = 0$, V_{CC} , Outputs Open	Ind.			105	mA
. (1)	Power Supply Current,	0 MHz, V _{CC} = Max,	Com.		5		μΑ
I _{CC} ⁽¹⁾	Standby Mode	$V_{IN} = 0$, V_{CC} , Outputs Open	Ind		5		μΑ
I _{os}	Output Short Circuit Current	V _{OUT} = 0.5V; V _{CC} = 5V; TA = 25°C				-150	mA
V _{IL}	Input Low Voltage	Min < V _{CC} < Max		-0.5		0.8	V
V _{IH}	Input High Voltage			2.0		V _{CC} +1	V
V _{OL}	Output Low Voltage	$V_{CC} = Min, All Outputs$ $I_{OL} = -16 \text{ mA}$ Com, Ind.				0.5	V



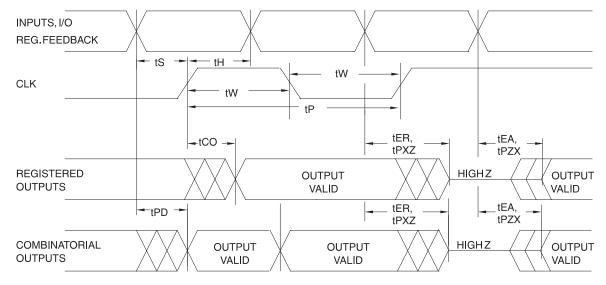


4.1 DC Characteristics

Symbol	Parameter	Condition		Min	Тур	Max	Units
V _{OH}	Output High Voltage	$V_{CC} = Min$ $I_{OL} = -3.2 \text{ mA}$		2.4			V
	Contract Law Comment	V Min	Com.	24			Л
I _{OL}	Output Low Current	V _{CC} = Min	Ind.	12			mA
I _{OH}	Output High Current	V _{CC} = Min	Com., Ind.	4			mA

Note: 1. All I_{CC} parameters measured with outputs open. Data is based on Atmel test patterns. Reading may vary with pattern.

4.2 AC Waveforms⁽¹⁾



Note: 1. Timing measurement reference is 1.5V. Input AC driving levels are 0.0V and 3.0V, unless otherwise specified.

4.3 AC Characteristics

		-12		-	15	
Symbol	Parameter	Min	Max	Min	Max	Units
t _{PD}	Input or Feedback to Non-registered Output	3	12	3	15	ns
t _{CF}	Clock to Feedback		6		8	ns
t _{CO}	Clock to Output	2	8	2	10	ns
t _S	Input or Feedback Setup Time	10		12		ns
t _H	Input Hold Time	0		0		ns
t _P	Clock Period	12		16		ns
t _W	Clock Width	6		8		ns
	External Feedback 1/(t _S + t _{CO})		55		45	MHz
f _{MAX}	Internal Feedback 1/(t _S + t _{CF})		62		50	MHz
	No Feedback 1/(t _P)		83		62	MHz
t _{EA}	Input to Output Enable – Product Term	3	12	3	15	ns
t _{ER}	Input to Output Disable – Product Term	2	15	2	15	ns
t _{PZX}	OE pin to Output Enable	2	12	2	15	ns
t _{PXZ}	OE pin to Output Disable	1.5	12	1.5	15	ns

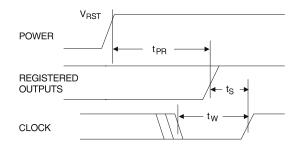


4.5 Power-up Reset

The ATF16V8CZ's registers are designed to reset during power-up. At a point delayed slightly from V_{CC} crossing V_{RST} , all registers will be reset to the low state. As a result, the registered output state will always be high on power-up.

This feature is critical for state machine initialization. However, due to the asynchronous nature of reset and the uncertainty of how V_{CC} actually rises in the system, the following conditions are required:

- 1. The V_{CC} rise must be monotonic, from below 0.7V,
- 2. After reset occurs, all input and feedback setup times must be met before driving the clock term high, and
- 3. The signals from which the clock is derived must remain stable during t_{PR}.



Parameter	Description		Max	Units
t _{PR}	Power-up Reset Time	600	1,000	ns
V _{RST}	Power-up Reset Voltage	3.8	4.5	V

4.6 Preload of Registered Outputs

The ATF16V8CZ's registers are provided with circuitry to allow loading of each register with either a high or a low. This feature will simplify testing since any state can be forced into the registers to control test sequencing. A JEDEC file with preload is generated when a source file with vectors is compiled. Once downloaded, the JEDEC file preload sequence will be done automatically by approved programmers.

5. Security Fuse Usage

A single fuse is provided to prevent unauthorized copying of the ATF16V8CZ fuse patterns. Once programmed, fuse verify and preload are inhibited. However, the 64-bit User Signature remains accessible.

The security fuse should be programmed last, as its effect is immediate.



6. Input and I/O Pin-keeper Circuits

The ATF16V8CZ contains internal input and I/O pin-keeper circuits. These circuits allow each ATF16V8CZ pin to hold its previous value even when it is not being driven by an external source or by the device's output buffer. This helps insure that all logic array inputs are at known, valid logic levels. This reduces system power by preventing pins from floating to indeterminate levels. By using pin-keeper circuits rather than pull-up resistors, there is no DC current required to hold the pins in either logic state (high or low).

These pin-keeper circuits are implemented as weak feedback inverters, as shown in the Input Diagram below. These keeper circuits can easily be overdriven by standard TTL- or CMOS-compatible drivers. The typical overdrive current required is $40 \, \mu A$.

Figure 6-1. Input Diagram

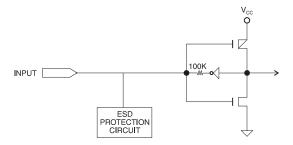


Figure 6-2. I/O Diagram

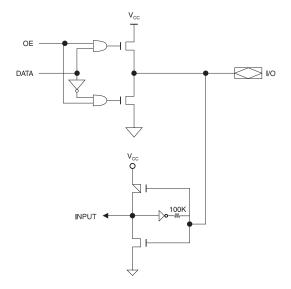
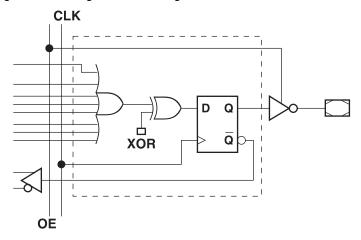


Figure 8-1. Registered Configuration for Registered Mode⁽¹⁾⁽²⁾



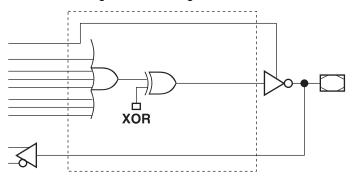
es: 1. Pin 1 controls common CLK for the registered outputs.

Pin 11 controls common \overline{OE} for the registered outputs.

Pin 1 and Pin 11 are permanently configured as CLK and \overline{OE} .

2. The development software configures all the architecture control bits and checks for proper pin usage automatically.

Figure 8-2. Combinatorial Configuration for Registered Mode⁽¹⁾⁽²⁾



Notes: 1. Pin 1 and Pin 11 are permanently configured as CLK and \overline{OE} .

2. The development software configures all the architecture control bits and checks for proper pin usage automatically.



Figure 8-3. Registered Mode Logic Diagram

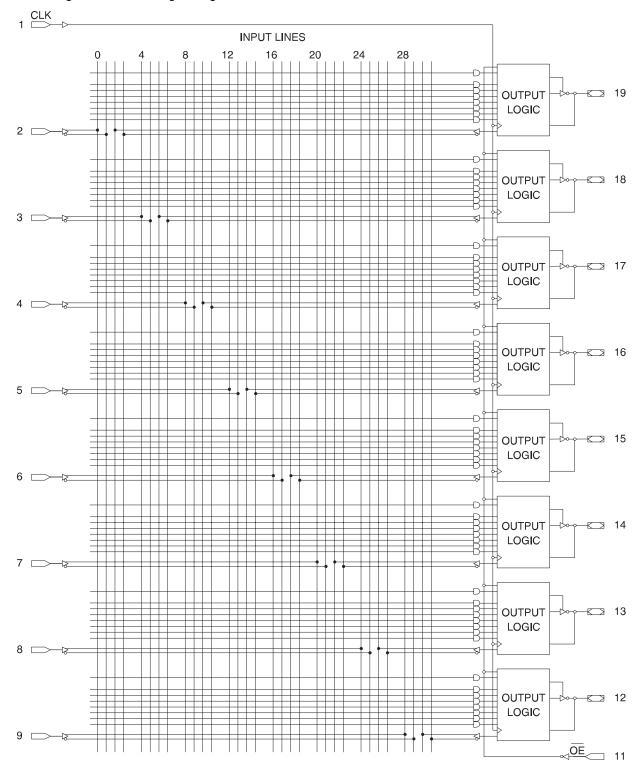


Figure 9-2. Complex Mode Logic Diagram

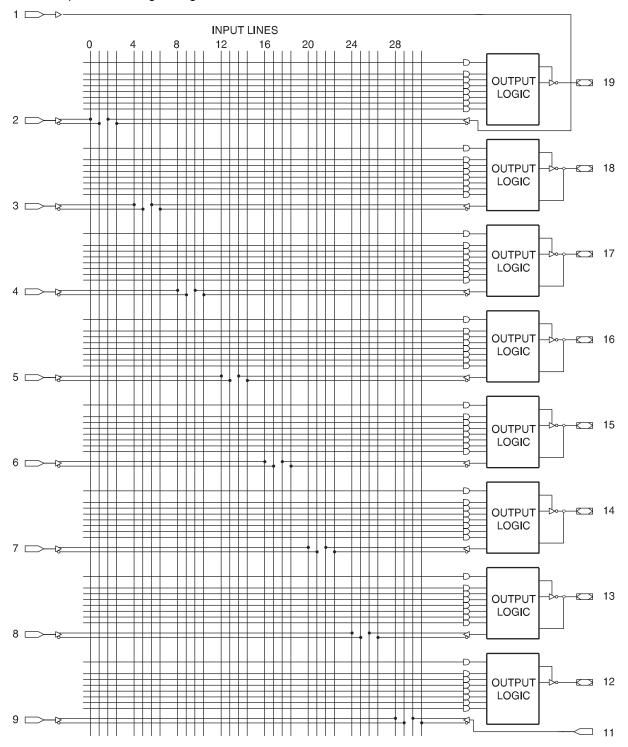
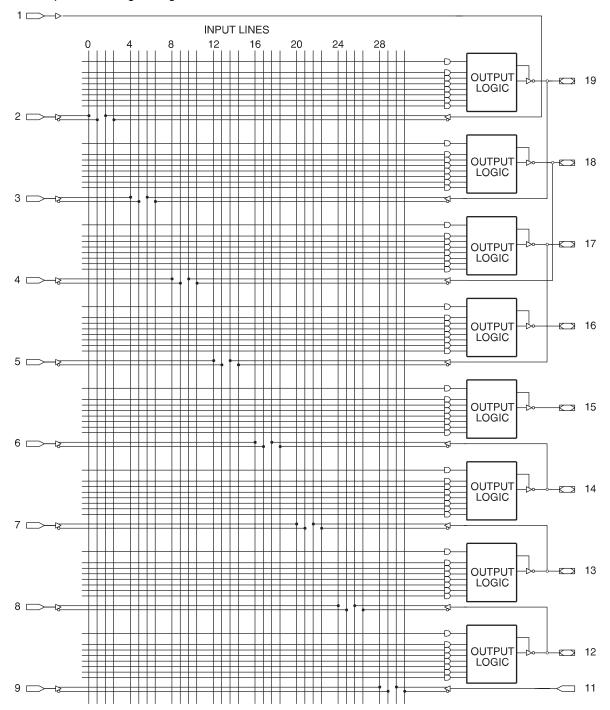
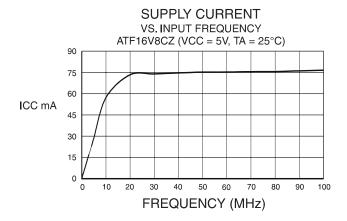


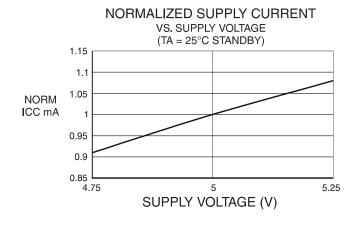


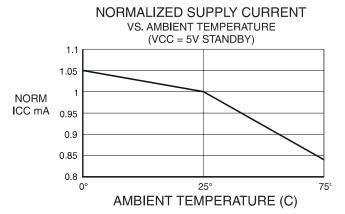
Figure 9-3. Simple Mode Logic Diagram

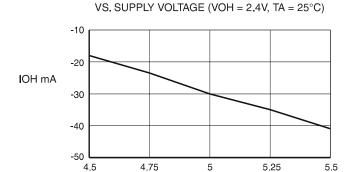


9.1 Test Characterization Data



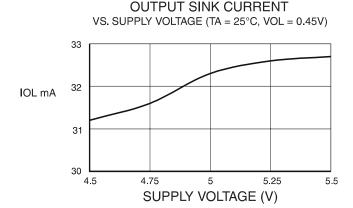


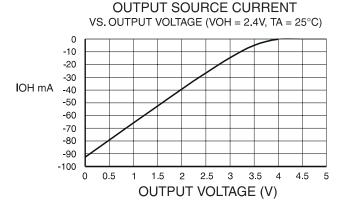




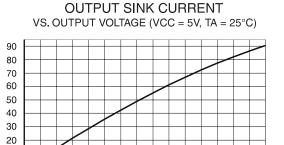
OUTPUT SOURCE CURRENT

SUPPLY VOLTAGE (V)









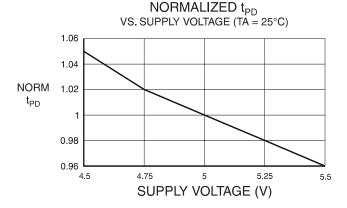
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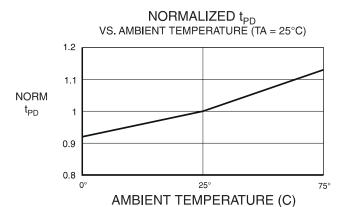
OUTPUT VOLTAGE (V)

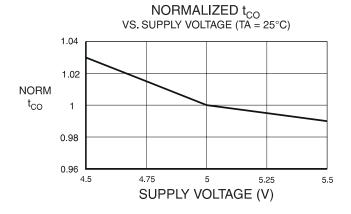
IOL mA

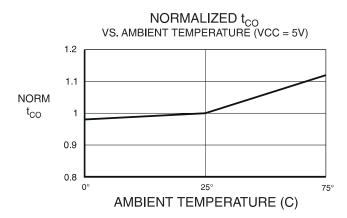
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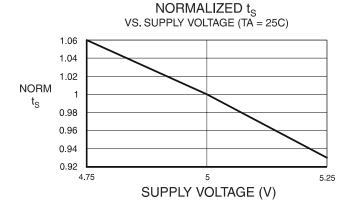
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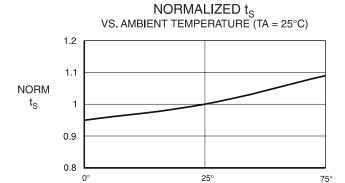




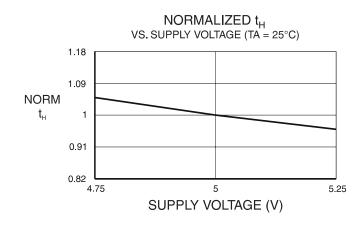


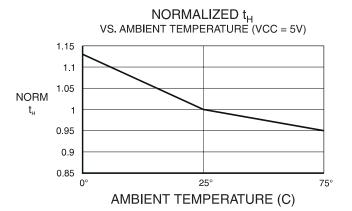


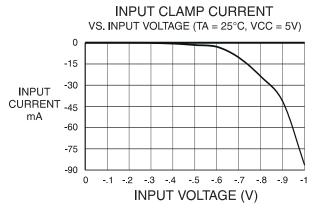


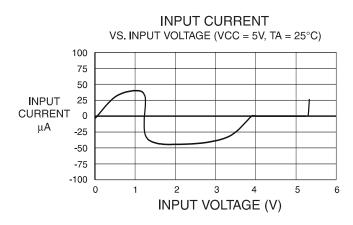


AMBIENT TEMPERATURE (C)











10. Ordering Information

10.1 Standard Package Options

t _{PD} (ns)	t _s (ns)	t _{co} (ns)	Ordering Code	Package	Operation Range	
			ATF16V8CZ-12JC	20J		
12	10	8	ATF16V8CZ-12PC	20P3	Commercial	
12	10	0	ATF16V8CZ-12SC	20S	(0°C to 70°C)	
			ATF16V8CZ-12XC	20X		
		12 10	ATF16V8CZ-15JC	20J		
	10		10	ATF16V8CZ-15PC	20P3	Commercial
			ATF16V8CZ-15SC	20S	(0°C to 70°C)	
15			ATF16V8CZ-15XC	20X		
15			ATF16V8CZ-15JI	20J		
		10	ATF16V8CZ-15PI	20P3	Industrial	
	12	10	ATF16V8CZ-15SI	20S	(-40°C to 85°C)	
			ATF16V8CZ-15XI	20X		

Note: Shaded parts are being obsoleted in Q3-05 and being replaced by Green parts.

10.2 Using "C" Product for Industrial

To use commercial product for Industrial temperature ranges, down-grade one speed grade from the "I" to the "C" device (7 ns "C" = 10 ns "I") and de-rate power by 30%.

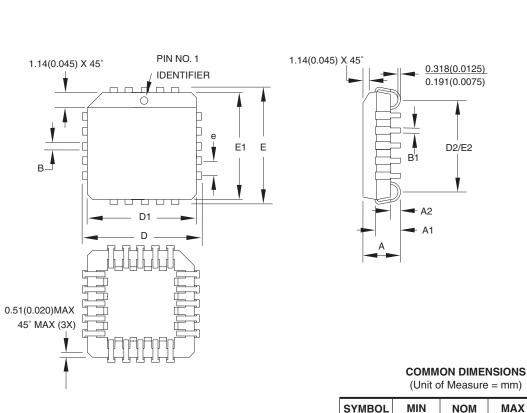
10.3 Green Package Options (Pb/Halide-free/RoHS Compliant)

t _{PD} (ns)	t _S (ns)	t _{CO} (ns)	Ordering Code	Package	Operation Range
			ATF16V8CZ-15JU ATF16V8CZ-15PU	20J 20P3	Industrial
15	12	10	ATF16V8CZ-15SU	20S	(-40°C to 85°C)
			ATF16V8CZ-15XU	20X	

	Package Type					
20J	20J 20-lead, Plastic J-leaded Chip Carrier (PLCC)					
20P3	20P3 20-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)					
20S	20-lead, 0.300" Wide, Plastic Gull-wing Small Outline (SOIC)					
20X	20-lead, 4.4 mm Wide, Plastic Thin Shrink Small Outline (TSSOP)					

11. Package Information

11.1 20J - PLCC



Notes:

- 1. This package conforms to JEDEC reference MS-018, Variation AA.
- Dimensions D1 and E1 do not include mold protrusion.
 Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
- 3. Lead coplanarity is 0.004" (0.102 mm) maximum.

(Offit of Measure = ITIIII)								
SYMBOL	MIN	NOM	MAX	NOTE				
Α	4.191	_	4.572					
A1	2.286	_	3.048					
A2	0.508	_	_					
D	9.779	_	10.033					
D1	8.890	_	9.042	Note 2				
E	9.779	_	10.033					
E1	8.890	_	9.042	Note 2				
D2/E2	7.366	_	8.382					
В	0.660	_	0.813					
B1	0.330	_	0.533					
е								

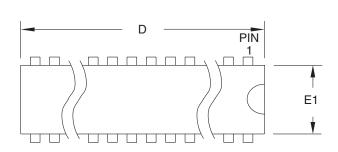
10/04/01

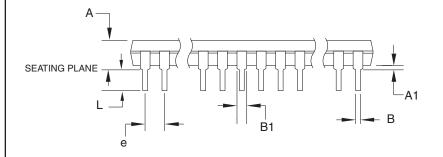
	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	20J, 20-lead, Plastic J-leaded Chip Carrier (PLCC)	20J	В

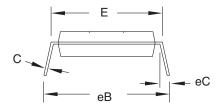




11.2 20P3 - PDIP







Notes:

- 1. This package conforms to JEDEC reference MS-001, Variation AD.
- Dimensions D and E1 do not include mold Flash or Protrusion.
 Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
Α	_	_	5.334	
A1	0.381	_	_	
D	24.892	_	26.924	Note 2
E	7.620	_	8.255	
E1	6.096	_	7.112	Note 2
В	0.356	_	0.559	
B1	1.270	_	1.551	
L	2.921	-	3.810	
С	0.203	_	0.356	
eB	-	_	10.922	
eC	0.000	_	1.524	
е	2.540 TYP			

1/23/04

		DRAWING NO.	REV.	
	2325 Orchard Parkway San Jose, CA 95131	20P3, 20-lead (0.300"/7.62 mm Wide) Plastic Dual Inline Package (PDIP)	20P3	D

11.3 20S - SOIC

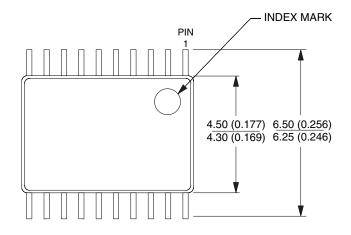
Dimensions in Millimeters and (Inches). Controlling dimension: Inches. JEDEC Standard MS-013 0.51(0.020) 0.33(0.013) 7.60 (0.2992) 10.65 (0.419) 7.40 (0.2914) 10.00 (0.394) PIN 1 ID PIN 1 -1.27 (0.050) BSC 13.00 (0.5118) 2.65 (0.1043) 12.60 (0.4961) 2.35 (0.0926) 0.30(0.0118) 0.10 (0.0040) 0.32 (0.0125) 0° ~ 8° 0.23 (0.0091) 1.27 (0.050) 0.40 (0.016) 10/23/03 TITLE DRAWING NO. REV. 2325 Orchard Parkway 20S, 20-lead, 0.300" Body, Plastic Gull Wing Small Outline (SOIC) 20S В San Jose, CA 95131

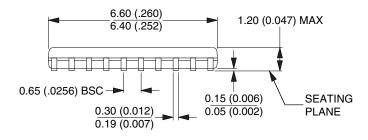


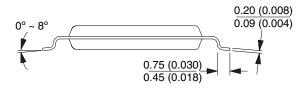


11.4 20X - TSSOP

Dimensions in Millimeters and (Inches). Controlling dimension: Millimeters. JEDEC Standard MO-153 AC







10/23/03

2325 Orchard Parkway San Jose, CA 95131 **TITLE 20X**, (Formerly 20T), 20-lead, 4.4 mm Body Width, Plastic Thin Shrink Small Outline Package (TSSOP)

DRAWING NO. 20X

С

REV.

12. Revision History

12.1 0453H

1. Green Package options added in 2005.





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Tel: (49) 71-31-67-0 Fax: (49) 71-31-67-2340

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Avenue de Rochepleine

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38521 Saint-Egreve Cedex, France

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